



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-09-27
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b> Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
2SD882	TCOT*BA0556C	A	Z6TA	2018-09-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	640.00	mg	Each	ECOPACK® 1
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	10.8-7.8-2.7	8	no lead	
Comment	Package: SOT-32			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	7.19	Die - Leadframe	11230
Lead	3.73	Soft solder	5830
Antimony trioxide	13.64	Mold compound	21313

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	3.73	Soft solder	5830
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	3.73	Soft solder	958879

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TCOT*BA0556C					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.641	mg	supplier	die	Silicon (Si)	7440-21-3		0.614	mg	957878	959
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	14041	14
				supplier	Passivation	Silicon Oxide	7631-86-9		0.011	mg	17161	17
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	7800	8
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.002	mg	3120	3
Leadframe	Copper & Its alloys	359.089	mg	supplier	alloy	Copper (Cu)	7440-50-8		283.680	mg	789999	443250
				supplier	alloy	Iron (Fe)	7439-89-6		53.864	mg	150002	84163
				supplier	alloy	Phosphorous (P)	12185-10-3		14.363	mg	39998	22442
				supplier	alloy	Nickel (Ni)	7440-02-0		7.182	mg	20001	11222
Soft solder	Solder	3.891	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	3.731	mg	958879	5830
				supplier	solder	Tin (Sn)	7440-31-5		0.070	mg	17991	109
				supplier	solder	Silver (Ag)	7440-22-4		0.090	mg	23130	140
Bonding wires	Other inorganic materials	0.401	mg	supplier	wire	Copper (Cu)	7440-50-8		0.401	mg	1000000	627
Encapsulation	Other inorganic materials	272.838	mg	supplier	mold compound	Silica (SiO2)	60676-86-0		256.467	mg	939997	400730
				supplier	mold compound	Antimony Oxide	1309-64-4		13.642	mg	50000	21316
				supplier	mold compound	Carbon Black	1333-86-4		2.729	mg	10003	4264
Connections coating	Solder	3.140	mg	supplier	alloy	Tin (Sn)	7440-31-5		3.140	mg	1000000	4906